



- NOTES:
- PLATING THICKNESS:  
ELECTRO Ni 1.27~8.89 MICRON(AT SOLDER PADS)  
ELECTRO Au 0.30~0.70 MICRON(AT SOLDER PADS)
  - CAMBER: 0.05 MAX.
  - \* MARK TO BE MATERIAL DIMENSION.
  - SEALING METHOD OF THIS PRODUCT SHALL BE SBAM WELD.

TOLERANCE XX ±1% XXX N.L.T.±0.13 ANGLES	REVISION	SBB ATTACHED EXCEPTIONS SHEET.				TITLE
	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	6035 X'tal PKG 2
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	PART NO.
90%MIN.A1203 (INA-301B BLACK)	Shigetomi	Yamahata	Ohba	Kumura	Sugi	S3560XTAL1
	Nov.11.02	Nov.11.02	Nov.11.02	Nov.11.02	Nov.11.02	REV. 0
						DWG NO.
						SHT/OF 1/6